Title (en)

Inductive structures for semiconductor integrated circuits.

Title (de)

Induktive Strukturen für halbleitende integrierte Schaltungen.

Title (fr)

Structures inductives pour circuits intégrés semi-conducteurs.

Publication

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Application

EP 94116854 A 19900817

Priority

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- JP 21383989 A 19890818

Abstract (en)

A variable inductance element integrable with a semiconductor integrated circuit comprises an electrically insulating substrate (1) having opposed first and second surfaces, an electrical conductor disposed in a first spiral (62) on the first surface of the substrate (1), an electrically insulating film (61) disposed on the first surface and the first spiral (62), a second electrical conductor disposed in a second spiral (2) on the electrically insulating film (61) and inductively coupled to the first spiral (62), and means (68, 70) for producing and controlling an electrical current flow through one of said spirals.

IPC 1-7

H01F 17/00; H01F 27/28

IPC 8 full level

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CPC (source: EP US)

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